MARKED-UP VERSION OF REPLACEMENT PARAGRAPHS

--A packaging substrate which is also referred to as a "base material" herein may be a conventional substrate or an improved substrate thereof. As suitable base materials, there are, for example, a hard resin substrate, a metal substrate, a ceramic substrate, and a printed substrate. The hard resin substrate includes, for example, a substrate prepared from a resin reinforced with a reinforcing material like a glass fiber, a Kevlar™ resin, etc., and a substrate prepared from a glass polyimide resin, a glass epoxy resin, a glass bismaleiimide triazine (BT), a glass polyphenylene ether (PPE) resin, etc. The metal substrate comprises a base material such as aluminum, iron, or copper, having applied thereon via an organic insulation film (for example, a polyimide resin, an epoxy resin, etc.) a circuit pattern. Specifically, they include an IMS substrate, a metal core substrate, and an enamel substrate. The ceramic substrate is a base material of a high-purity fine ceramic, on which a circuit pattern has been formed. As suitable ceramic substrates, there are an alumina (aluminum oxide) [aluminum] substrate, an AIN substrate (an aluminum nitride substrate), and a low-temperature sintered substrate. The printed substrate includes various substrates having a circuit pattern formed on them based on a print wiring technique. As a typical example of such substrates, there is a built-up substrate. The built-up substrate is a multi-layer printed wiring substrate having conductive layers and

insulation layers sequentially laminated on the base material by plating or screen printing, as is known.--

--In the wiring substrate 10 shown in Fig. 9, a high-elasticity underlayer 4 is formed in a predetermined film thickness on one surface of a rigid plastic base material 1. A low-elasticity underlayer 3 is formed on this high-elasticity underlayer 4 escaping from the region of an external-connection terminal 12. A rerouted wiring 17 and the external-connection terminal 12 are formed to cover the high-elasticity underlayer 4 and the low-elasticity underlayer 3. [The rerouted wiring 17 and the conductor 2 are electrically connected with each other via a connection via-hole 15.]--

--In the wiring substrate 10 shown in Fig. 10, a high elasticity underlayer 4 is formed in different film thicknesses on one surface of a rigid plastic base material 1. That is, the high-elasticity underlayer 4 is formed in a predetermined pattern so that the region corresponding to an external-connection terminal 12 has a large thickness and other regions have a small thickness. On the high-elasticity underlayer 4, a low-elasticity underlayer 3 is formed so that the total thickness of the high-elasticity underlayer 4 and the low-elasticity underlayer 3 becomes constant to match the largest thickness of the high-elasticity underlayer 4. The external-connection terminal 12 is formed on the high-elasticity underlayer 4. An electronic-part

mounting pad 16 and a rerouted wiring 17 are formed on the low-elasticity underlayer 3. [The electronic-part mounting pad 16 and the conductor 2 are electrically connected to each other via a connection via-hole 15.]--

--In the wiring substrate 10 shown in Fig. 11, a high-elasticity underlayer 4 is formed on one surface of a rigid plastic base material 1 in such a manner that the high-elasticity underlayer 4 is positioned only in the region beneath an external-connection terminal 12. Adjacent to the high-elasticity underlayer 4, a low-elasticity underlayer 3 is formed in a film-thickness distribution as shown in the drawing. That is, the low elasticity underlayer 3 has a large film thickness in the region beneath a electronic-part mounting pad 16 and a rerouted wiring 17, and at the same time, has a very small film thickness at the other portion beneath the high-elasticity underlayer 4. The total thickness of the composite underlayer of the high-elasticity underlayer 4 and the low-elasticity underlayer 3 is constant. The external-connection terminal 12 is formed on the high-elasticity underlayer 4. The electronic-part mounting pad 16 and the rerouted wiring 17 are formed on the low-elasticity underlayer 3. [The electronic-part mounting pad 16 and the conductor 2 are electrically connected to each other via a connection via-hole 15.]--